



Material Content Data Sheet



Sales Product Name		IR3826MTRPBF		Issued		3. July 2019		
MA#		MA002005492						
Package		PG-IQFN-22-1		Weight*		84.88 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	0.393	0.46	0.46	4625	4625
chip_2	inorganic material	silicon	7440-21-3	1.430	1.69	1.69	16852	16852
chip_3	inorganic material	silicon	7440-21-3	0.210	0.25	0.25	2479	2479
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		116	
	non noble metal	zinc	7440-66-6	0.039	0.05		464	
	non noble metal	iron	7439-89-6	0.788	0.93		9284	
wire	non noble metal	copper	7440-50-8	31.997	37.70	38.69	376983	386847
	noble metal	gold	7440-57-5	0.295	0.35		3470	
	non noble metal	copper	7440-50-8	0.937	1.10	1.45	11044	14514
encapsulation	organic material	carbon black	1333-86-4	0.091	0.11		1072	
	plastics	epoxy resin	-	4.688	5.52		55230	
	inorganic material	silicondioxide	60676-86-0	40.732	47.99	53.62	479907	536209
leadfinish	noble metal	palladium	7440-05-3	0.003	0.00		31	
	noble metal	gold	7440-57-5	0.004	0.00		50	
	non noble metal	nickel	7440-02-0	0.077	0.09	0.09	911	992
plating	noble metal	palladium	7440-05-3	0.005	0.01		63	
	noble metal	gold	7440-57-5	0.009	0.01		101	
	non noble metal	nickel	7440-02-0	0.157	0.18	0.20	1847	2011
solder	noble metal	silver	7440-22-4	0.075	0.09		887	
	non noble metal	tin	7440-31-5	0.151	0.18		1774	
	non noble metal	lead	7439-92-1	2.785	3.28	3.55	32810	35471
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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